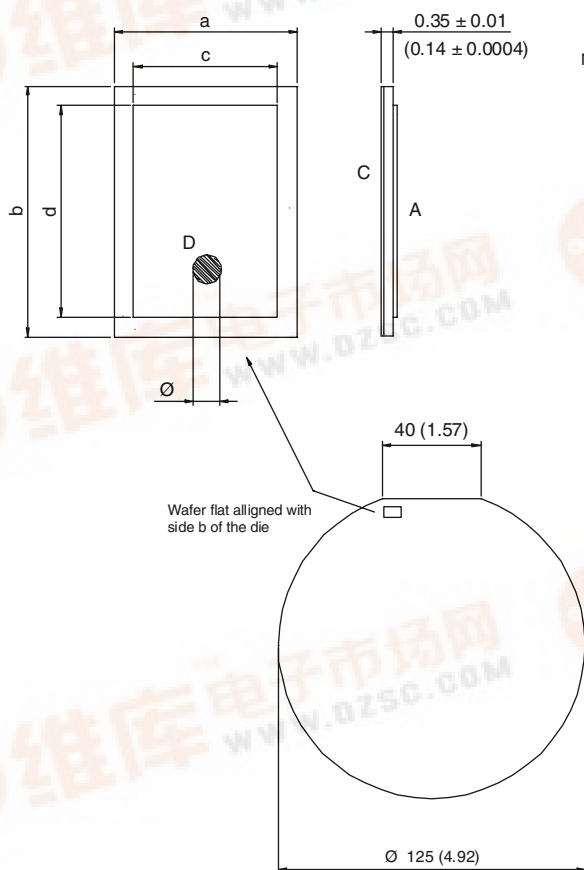


International IOR Rectifier

Bulletin I0503J 12/99

SC105.....5. Series

SCHOTTKY DIE 105 x 125 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

2. CONTROLLING DIMENSION: (INCH).

3. DIMENSIONS AND TOLERANCES:

a = 3.18 ± 0.05
(0.125 ± 0.002)
b = 2.67 ± 0.05
(0.105 ± 0.002)
c = 3.02 ± 0.003
(0.119 ± 0.0001)
d = 2.51 ± 0.003
(0.099 ± 0.0001)
Ø = 0.7 ± 0.1
(0.03 ± 0.004)

4. LETTER DESIGNATION:

A = Anode (Top Metal)
C = Cathode (Back Metal)
D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade
SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC105 R 015x5x	125	15	3000	n.a. contact factory		
SC105 S 020x5x	125	20	n.a. contact factory			
SC105 S 030x5x	150	30	220	100	0.49 @ 15A	TO-220
SC105 S 045x5x	150	45	150	75	0.54 @ 15A	TO-247
SC105 S 060x5x	150	60	110	60	0.60 @ 15A	TO-247
SC105 H 045x5x	175	45	35	10	0.62 @ 15A	TO-220
SC105 H 100x5x	175	100	12	7	0.86 @ 15A	TO-247
SC105 H 150x5x	175	150	15	7	1.00 @ 15A	TO-220

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC105xxxx A 5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 4 kÅ	Ag 6 kÅ
SC105xxxx S 5x	Solderable	Ti 2 kÅ	Ni 6 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 4 kÅ	Ag 6 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

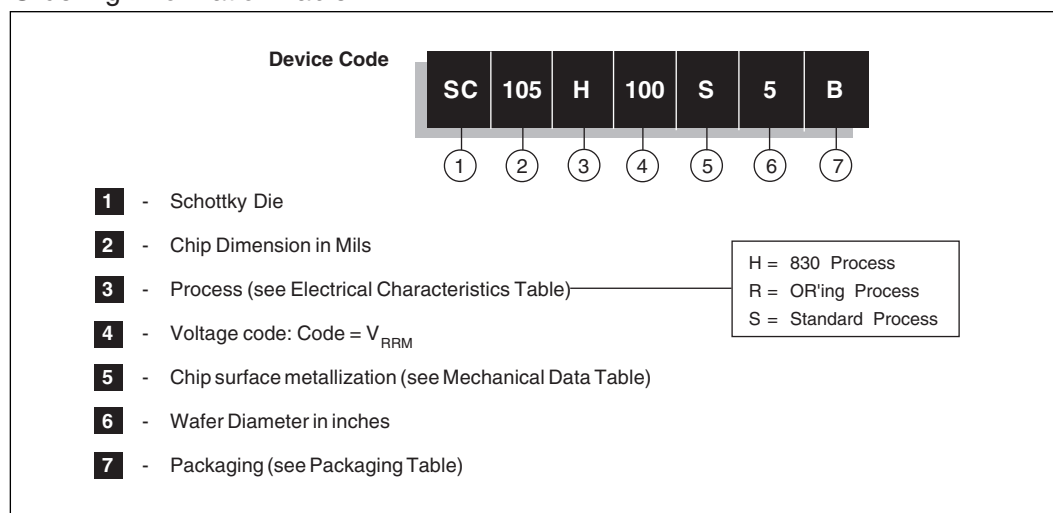
Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

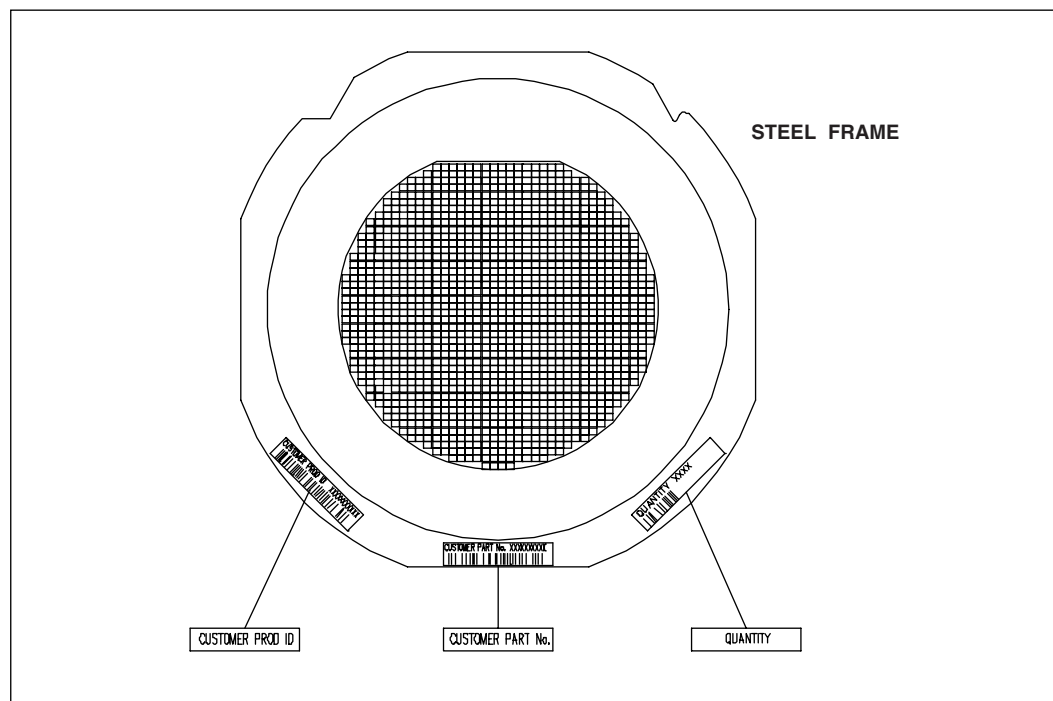
Packaging

Device #	Description	Minimum Order Quantity Wafer in Sale Package
SC105xxxxx B	Inked Probed Unsawn Wafer (Wafer in Box)	1150
SC105xxxxx R	Probed Die in Tape & Reel	3000
SC105xxxxx P	Probed Die in Waffle Pack	1150
SC105xxxxx F	Inked Probed Sawn Wafer on Film	1150

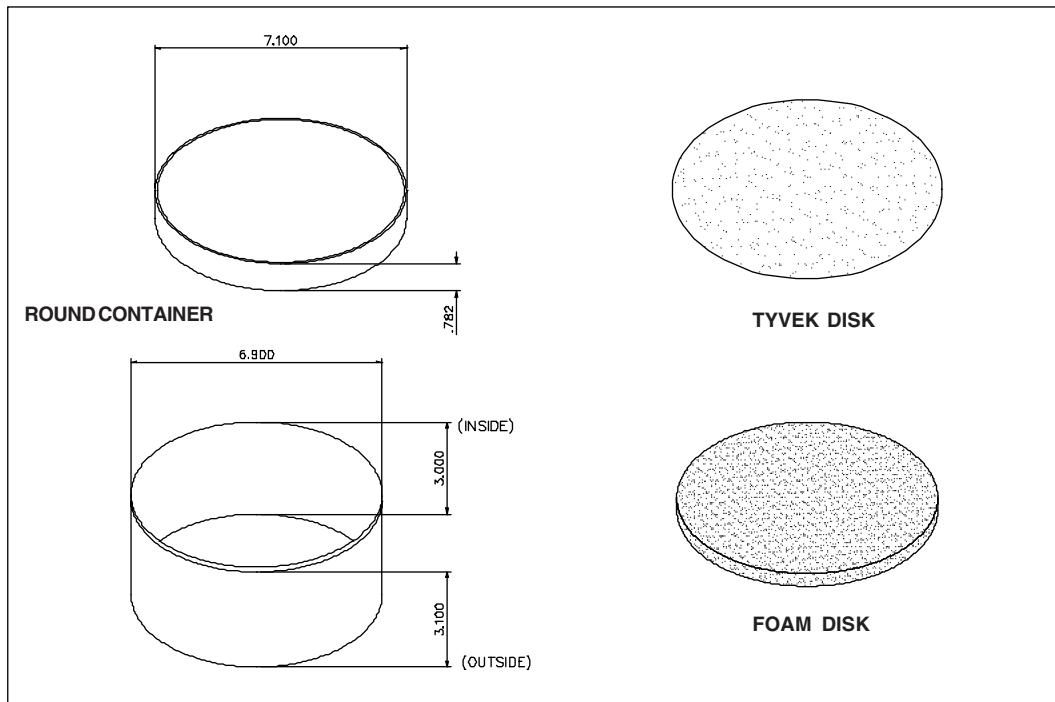
Ordering Information Table



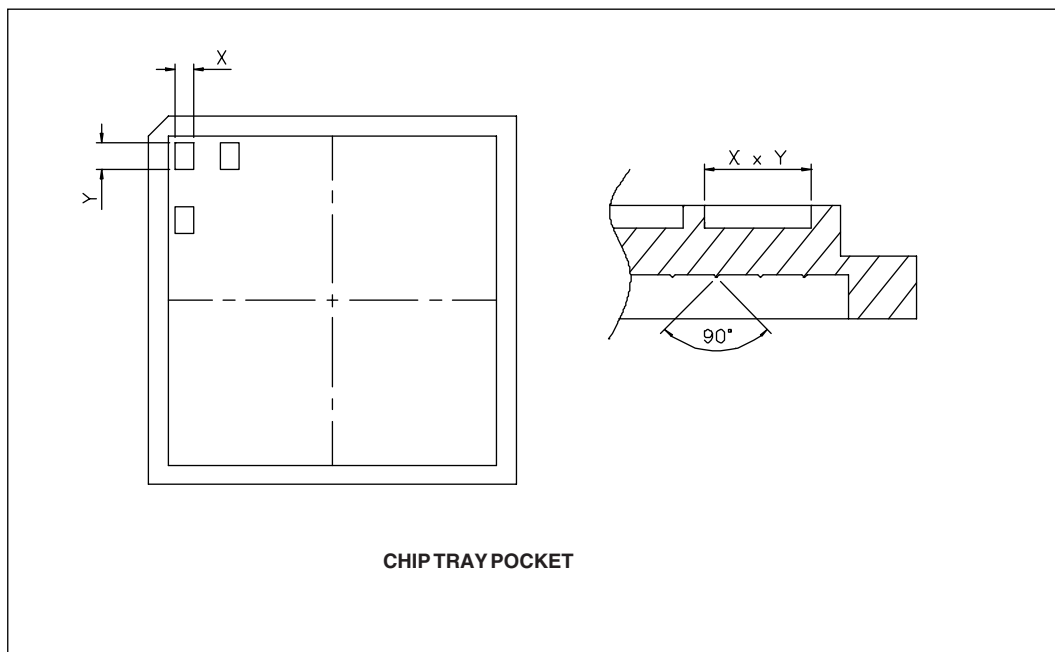
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

